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**IN THE CLAIMS**

1. (Currently Amended) A circuit material comprising a layer of a dielectric liquid crystalline composite, the composite comprising
  - a liquid crystalline polymer;
  - a particulate filler composition comprising a combination of a mineral filler and an organic filler silica and polytetrafluoroethylene; and
  - a fibrous web, wherein the composite has a dielectric constant of less than about 3.8 at frequencies higher than or equal to 1 GHz, a dissipation factor of less than or equal to about 0.007, and a UL-94 rating of V-1 or better.
2. (Currently Amended) The circuit material of Claim 1 further comprising a copper conductive layer, wherein the particulate filler comprises silica and polytetrafluoroethylene the bond strength between the conductive layer and liquid crystalline composite layer is greater than or equal to about 1 pli at 200°C.
3. (Currently Amended) The circuit material of Claim 1, wherein the particulate filler silica is treated with an coupling agent.
4. (Original) The circuit material of Claim 1, wherein the composite further has a water absorption of less than about 0.1%.
5. (Original) The circuit material of Claim 1, further comprising a first conductive layer disposed on one side of the composite layer.
6. (Original) The circuit material of claim 5, wherein the first conductive layer is copper.
7. (Original) The circuit material of claim 5, further comprising a second conductive layer disposed on a side of the composite layer opposite the first conductive layer.

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8. (Original) The circuit material of claim 5, wherein the second conductive layer is copper.
9. (Currently Amended) A circuit, comprising  
a dielectric substrate layer, wherein the dielectric substrate comprises  
a liquid crystalline polymer,  
a particulate filler composition comprising a combination of ~~a mineral filler and an organic filler~~ silica and polytetrafluoroethylene, and  
a fibrous web; and  
a circuit layer disposed on the dielectric substrate layer, wherein the circuit layer, the circuit has a dielectric constant of less than about 3.8, a dissipation factor of less than about 0.007 measured between 1 and 10 GHz, and a UL-94 rating of V-1 or better.
10. (Original) The circuit of claim 9, wherein the circuit layer is copper.
11. (Original) The circuit of claim 9, further comprising a conductive layer disposed on a side of the dielectric substrate opposite the first circuit layer.
12. (Original) The circuit of claim 11, wherein the conductive layer is copper.
13. (Original) The circuit of claim 8, wherein the conductive layer is patterned to form a second circuit layer.

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14. (Currently Amended) A multi-layer circuit comprising:  
a first circuit, the first circuit comprising a first dielectric substrate layer and a first circuit layer;  
a second circuit, the second circuit comprising a second dielectric substrate layer and a second circuit layer; and  
a bond ply disposed between the first dielectric substrate layer and the second circuit layer; wherein at least one of the first dielectric substrate layer, the second dielectric substrate layer, or the bond ply comprises a liquid crystalline polymer, a particulate filler composition comprising a combination of ~~a mineral filler and an organic filler silica and~~ ~~polytetrafluoroethylene~~, and a fibrous web; and further wherein the multi-layer circuit has a dielectric constant of less than about 3.8, a dissipation factor of less than or equal to about 0.007 measured between 1 and 10 GHz, and a UL-94 rating of V-1 or better.

15. (Original) The multi-layer circuit of claim 14, wherein the circuit layers are copper.

16. (Previously Presented) The multi-layer circuit of claim 14, further comprising a resin coated conductive layer comprising a first conductive layer disposed on a flowable dielectric material, wherein the flowable dielectric material is disposed on a side of the first circuit layer opposite the first dielectric substrate layer.

17. (Canceled)

18. (Canceled)

19. (Canceled)

20. (Canceled)

21. (Canceled)

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22. (Currently Amended) A circuit material comprising  
a conductive layer; and  
a layer of a liquid crystalline composite disposed on the conductive layer, the  
composite comprising  
a liquid crystalline polymer,  
a particulate filler composition, wherein the particulate filler composition comprises  
~~an organic filler and a mineral filler~~ silica and polytetrafluoroethylene; and  
a fibrous web;  
wherein the bond strength between the conductive layer and the liquid crystalline composite  
layer is greater than or equal to about 1 pli measured at 200°C.

23. (Previously Presented) The circuit material of claim 22, wherein the ~~mineral filler~~  
silica is treated with a coupling agent that is a silane that bonds to the ~~mineral filler~~silica and  
to the liquid crystalline polymer.

24. (Currently amended) A liquid crystalline composite, disposed on a conductive layer,  
the composite comprising  
a liquid crystalline polymer;  
a particulate filler composition, wherein the particulate filler composition comprises a  
combination of silica and polytetrafluoroethylene; and  
a fibrous web,  
wherein the bond strength between the conductive layer and the liquid crystalline composite  
layer is greater than or equal to about 1 pli measured at 200°C.